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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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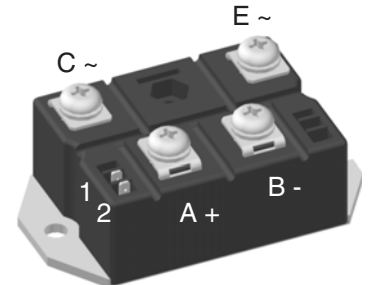
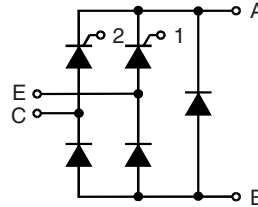


Half Controlled Single Phase Rectifier Bridge, B2HKF with Freewheeling Diode

$$I_{dAV} = 82/123 \text{ A}$$

$$V_{RRM} = 1200-1600 \text{ V}$$

V_{RSM} V_{DSM} V	V_{RRM} V_{DRM} V	Type	
1300	1200	VHF 85-12io7	VHF 125-12io7
1500	1400	VHF 85-14io7	VHF 125-14io7
1700	1600		VHF 125-16io7



Symbol	Conditions	Maximum Ratings		
		VHF 85	VHF 125	
I_{dAV}	$T_C = 85^\circ\text{C}$; module per leg	82	123	A
I_{FRMS}, I_{TRMS}		58	89	A
I_{FSM}, I_{TSM}	$T_{VJ} = 45^\circ\text{C}$; $t = 10 \text{ ms}$ (50 Hz), sine $V_R = 0 \text{ V}$;	1150	1500	A
	$t = 8.3 \text{ ms}$ (60 Hz), sine	1230	1600	A
I^2t	$T_{VJ} = T_{VJM}$; $t = 10 \text{ ms}$ (50 Hz), sine $V_R = 0 \text{ V}$;	1000	1350	A
	$t = 8.3 \text{ ms}$ (60 Hz), sine	1070	1450	A
$(di/dt)_{cr}$	$T_{VJ} = T_{VJM}$; repetitive; $I_T = 50 \text{ A}$; $f = 400 \text{ Hz}$; $t_p = 200 \mu\text{s}$; $V_D = 2/3 V_{DRM}$;		150	A/ μs
	$I_G = 0.3 \text{ A}$; non repetitive; $di_G/dt = 0.3 \text{ A}/\mu\text{s}$; $I_T = 1/3 I_{dAV}$		500	A/ μs
$(dv/dt)_{cr}$	$T_{VJ} = T_{VJM}$; $V_{DR} = 2/3 V_{DRM}$; $R_{GK} = \infty$; method 1 (linear voltage rise)		1000	V/ μs
V_{RGM}		10		V
P_{GM}	$T_{VJ} = T_{VJM}$; $t_p = 30 \mu\text{s}$	≤ 10		W
	$I_T = I_{TAVM}$; $t_p = 500 \mu\text{s}$	≤ 5		W
	$t_p = 10 \text{ ms}$	≤ 1		W
P_{GAVM}		0.5		W
T_{VJ}		-40...+125		$^\circ\text{C}$
T_{VJM}		125		$^\circ\text{C}$
T_{stg}		-40...+125		$^\circ\text{C}$
V_{ISOL}	50/60 Hz RMS; $t = 1 \text{ min}$	2500		V~
	$I_{ISOL} \leq 1 \text{ mA}$; $t = 1 \text{ s}$	3000		V~
M_d	Mounting torque (M6)	$5 \pm 15\%$		Nm
	Terminal connection torque (M6)	$5 \pm 15\%$		Nm
Weight	typ.	300		g

Features

- Package with screw terminals
- Isolation voltage 3000 V~
- Planar passivated chips
- UL listing applied for

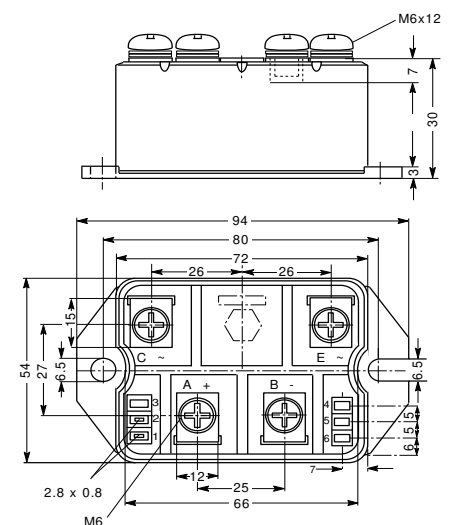
Applications

- DC motor control

Advantages

- Easy to mount with two screws
- Space and weight savings
- Improved temperature and power cycling

Dimensions in mm (1 mm = 0.0394")



Data according to IEC 60747 and refer to a single thyristor/diode unless otherwise stated.

IXYS reserves the right to change limits, test conditions and dimensions.

20080227a

Symbol	Conditions	Characteristic Values		
		VHF 85	VHF 125	
I_R, I_D	$V_R = V_{RRM}; V_D = V_{DRM}; T_{VJ} = T_{VJM}$ $T_{VJ} = 25^\circ\text{C}$	≤ 5 ≤ 0.3		mA mA
V_F, V_T	$I_F, I_T = 200 \text{ A}; T_{VJ} = 25^\circ\text{C}$	≤ 1.75	≤ 1.57	V
V_{T0}	For power-loss calculations only	0.85	0.85	V
r_T	($T_{VJ} = 125^\circ\text{C}$)	6	3.5	m Ω
V_{GT}	$V_D = 6 \text{ V}; T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = -40^\circ\text{C}$	≤ 1.5 ≤ 1.6		V V
I_{GT}	$V_D = 6 \text{ V}; T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = -40^\circ\text{C}$	≤ 100 ≤ 200		mA mA
V_{GD}	$T_{VJ} = T_{VJM}; V_D = \frac{2}{3} V_{DRM}$	≤ 0.2		V
I_{GD}	$T_{VJ} = T_{VJM}; V_D = \frac{2}{3} V_{DRM}$	≤ 5		mA
I_L	$I_G = 0.3 \text{ A}; t_G = 30 \mu\text{s};$ $T_{VJ} = 25^\circ\text{C}; di_G/dt = 0.3 \text{ A}/\mu\text{s}$	≤ 450		mA
I_H	$T_{VJ} = 25^\circ\text{C}; V_D = 6 \text{ V}; R_{GK} = \infty$	≤ 200		mA
t_{gd}	$T_{VJ} = 25^\circ\text{C}; V_D = 1/2 V_{DRM};$ $I_G = 0.3 \text{ A}; di_G/dt = 0.3 \text{ A}/\mu\text{s}$	≤ 2		μs
R_{thJC}	per thyristor (diode); DC current	0.65	0.46	K/W
	per module	0.108	0.077	K/W
R_{thJK}	per thyristor (diode); DC current	0.8	0.55	K/W
	per module	0.133	0.092	K/W
d_S	Creeping distance on surface	10		mm
d_A	Creepage distance in air	9.4		mm
a	Max. allowable acceleration	50		m/s ²

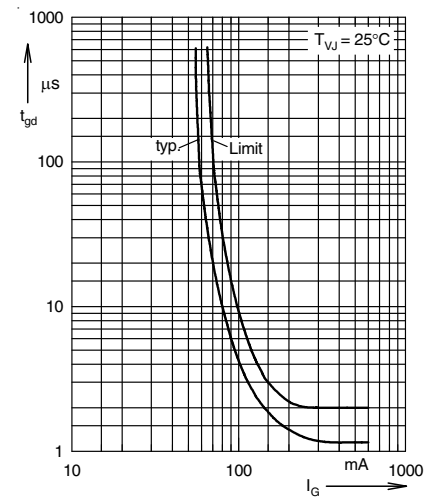


Fig. 1 Gate trigger delay time

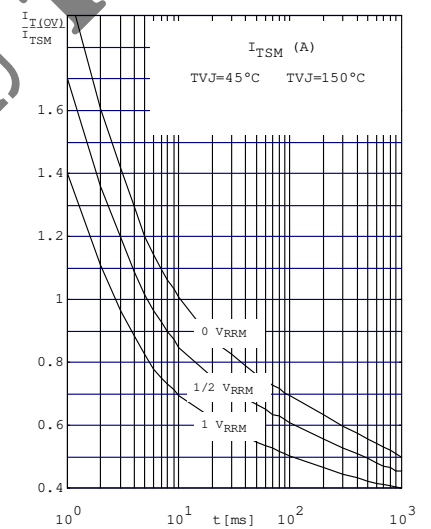


Fig. 2 Surge overload current per diode or thyristor
 I_{FSM}, I_{TSM} : Crest value t : duration

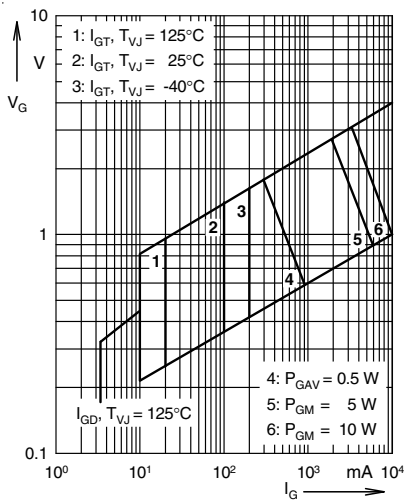


Fig.3 Gate trigger characteristic

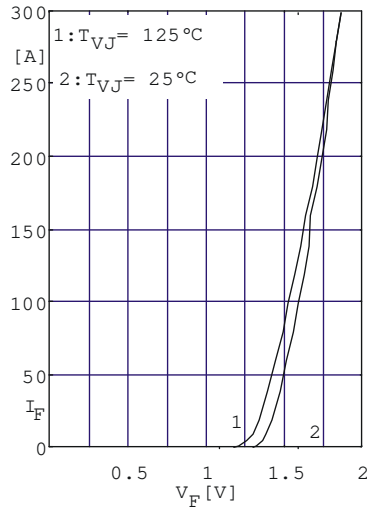


Fig. 4 Forward current vs. voltage drop per diode or thyristor

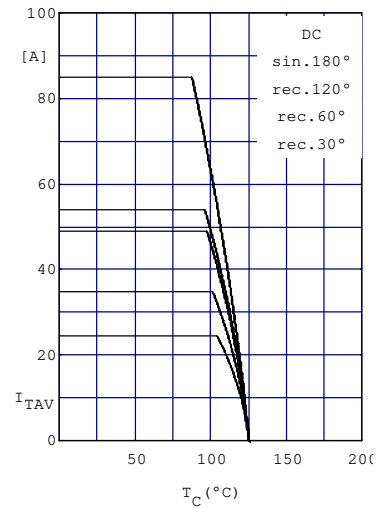


Fig.5 Maximum forward current at case temperature

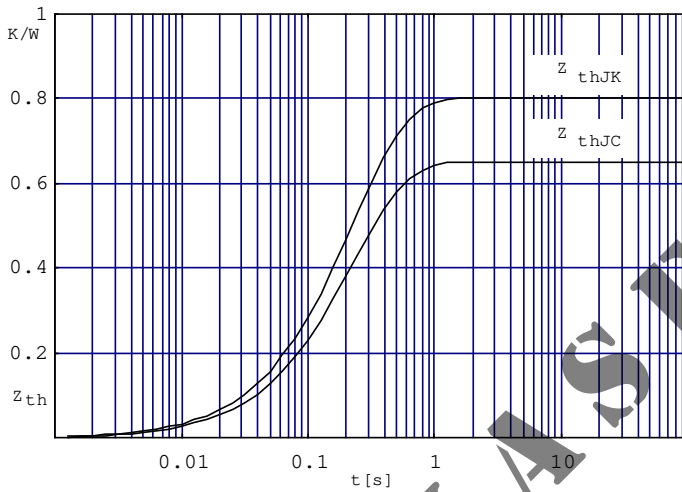


Fig. 6 Transient thermal impedance per thyristor or diode (calculated)

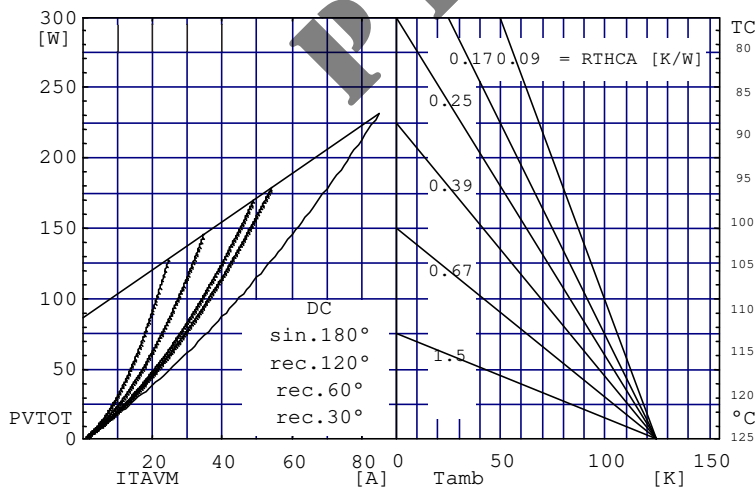


Fig. 7 Power dissipation vs. direct output current and ambient temperature

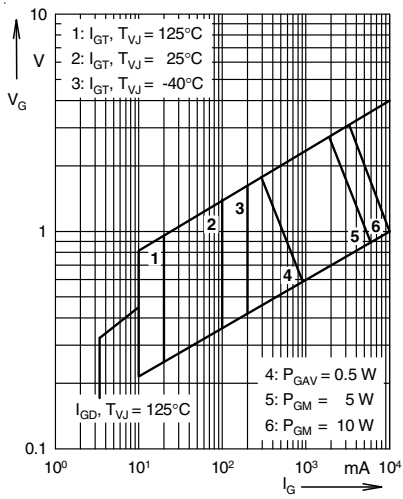


Fig. 3 Gate trigger characteristic

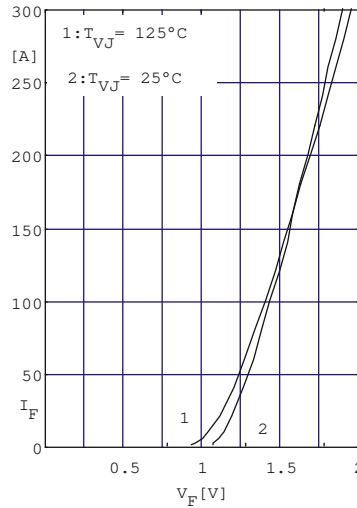


Fig. 4 Forward current vs. voltage drop per diode or thyristor

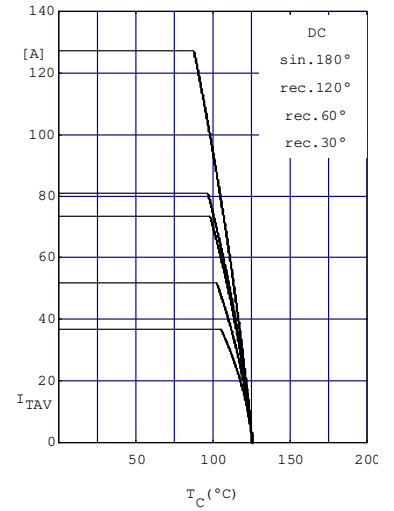


Fig. 5 Maximum forward current at case temperature

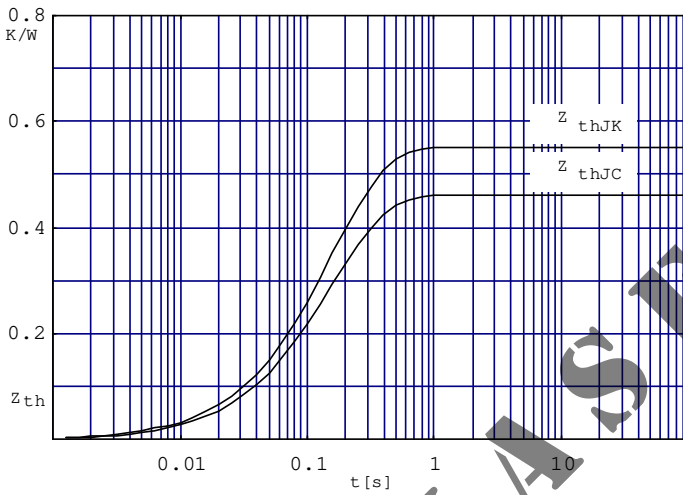


Fig. 6 Transient thermal impedance per thyristor or diode (calculated)

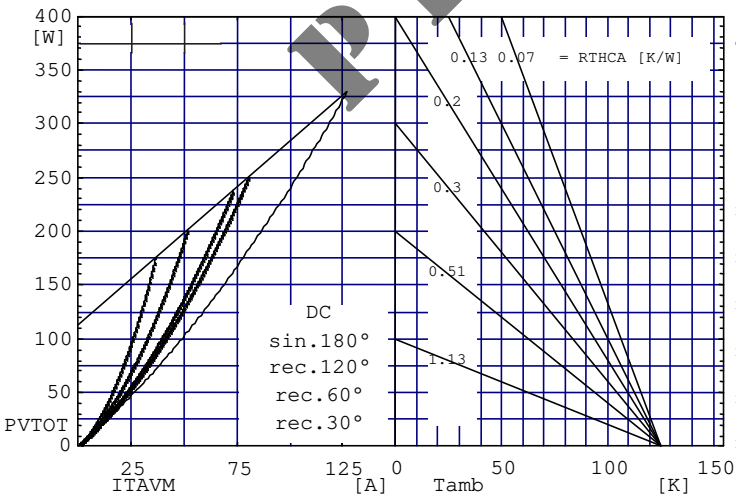


Fig. 7 Power dissipation vs. direct output current and ambient temperature